

Title (en)
HEAT DISSIPATING DEVICE AND CONTROLLER ASSEMBLY

Title (de)
WÄRMEABLEITVORRICHTUNG UND STEUERGERÄTEANORDNUNG

Title (fr)
DISPOSITIF DE DISSIPATION DE CHALEUR ET ENSEMBLE DE COMMANDE

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Application
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Priority

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Abstract (en)
[origin: WO2022194705A1] The invention relates to a heat dissipating device (10) and a controller assembly in a vehicle comprising such a heat dissipating device (10), which comprises a receiving area (11) that is open on at least one side and at least one mosaic segment (14) that is arranged in the receiving area (11) and comprises a thermally conductive and elastic compensation element (16) and a thermally conductive low-adherent contact region (18), wherein the at least one mosaic segment (14) is arranged in the receiving area (11) such that the thermally conductive and elastic compensation element (16) of the at least one mosaic segment (14) rests against the inner surface of the base (11.1) of the receiving area (11) and at least the thermally conductive low-adherent contact region (18) of the at least one mosaic segment (14) at least partly protrudes out of the receiving area (11) at the open face of the receiving area (11) lying opposite the base (11). The outer surface of the base (11.1) of the receiving area (11) forms a rigid first contact surface for a heat source (7) or for a heat sink (9), and the thermally conductive low-adherent contact region (18) of the at least one mosaic segment (14) forms a flexible second contact surface for the heat sink (9) or for the source (7).

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